

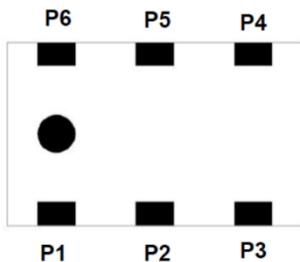
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process
- Surface process: Nickel tin electroplating (lead-free)

Specifications

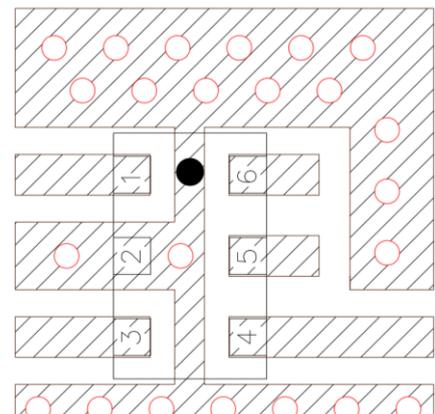
NO.	Items	Spec	Unit
1	Frequency range	300~2200	MHz
2	Unbalanced Impedance	50	Ohms
3	Differential Balanced Imp.	50	Ohms
4	Return Loss at Unbalanced Port	12.2 min.	dB
5	Insertion Loss	1.6 max.	dB
6	Amplitude Difference	1.3 max.	dB
7	Phase Difference	180 ± 12	deg
8	CMRR	15 typ.	dB
9	Operating Temperature	-40 ~ +85	°C
10	Power	2	W
Operating & Storage Condition (Component)			
Operation Temperature Range: -55°C ~ +145°C			
Storage Temperature Range: -40°C ~ +85°C			
Storage Condition before Soldering (Included packaging material)			
Storage Temperature Range: +5 ~ +40 °C			
Humidity: 30 to 70% relative humidity			

Construction & Dimensions

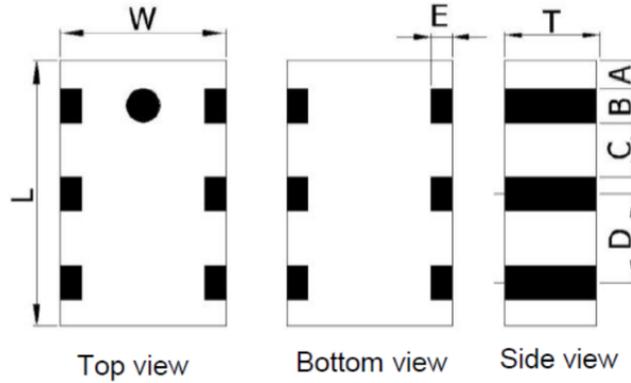


PIN	Connection
P1	Unbalance Port
P2	GND
P3	Balance Port
P4	Balance Port
P5	NC
P6	NC

Mounting Considerations



Dimensions



Symbol	L	W	T	A	B	C	D	E
Dimension (mm)	3.2 ± 0.15	1.60 ± 0.15	0.95 max.	0.33 ± 0.1	0.56 ± 0.1	0.43 ± 0.1	1.0 ± 0.1	0.30 ± 0.1

Typical Electrical Characteristics (T=25°C)

